

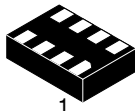
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

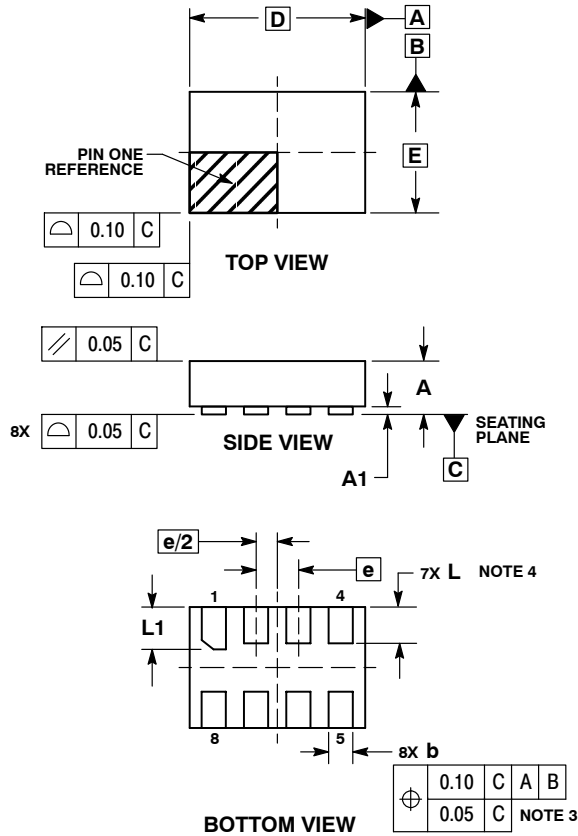


ULLGA8, 1.45x1.0, 0.35P
CASE 613AA-01
ISSUE A

DATE 05 FEB 2008



SCALE 8:1

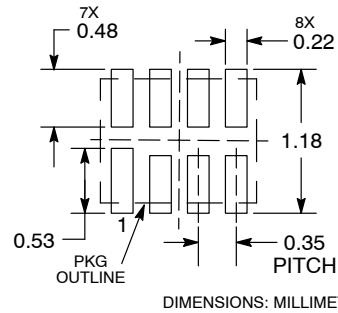


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.45	BSC
E	1.00	BSC
e	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT
SOLDERMASK DEFINED*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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